

ZPMV2

December 7, 2009

Wiring, Printed - Component

CAMPTECH II CIRCUITS INC

E80735

81 BENTLEY ST, MARKHAM, ON L3R 3L1 CANADA

Type	Cond Width			SS/ DS	Max Area Diam mm(in)	Solder Limits		Max Oper Temp C	Flame Class	Meets UL796 DSR	C T I
	Min mm(in)	Min Edge mm(in)	Cond Thk mic(mil)			C	sec				
Multi layer printed wiring boards.											
ML1	0.18 (0.007)	0.53 (0.021)	17 (0.67) Int:68.58	DS	38.1 (1.5)	288	20	130	-	▲	-
ML1-0	0.18 (0.007)	0.53 (0.021)	17 (0.67) Int:68.58	DS	38.1 (1.5)	288	20	130	V-0	▲	-
ML2	0.18 (0.007)	0.53 (0.021)	17 (0.67) Int:68.58	DS	38.1 (1.5)	274	15	130	-	▲	-
ML2-0	0.18 (0.007)	0.53 (0.021)	17 (0.67) Int:68.58	DS	38.1 (1.5)	274	15	130	V-0	▲	-
ML3	0.18 (0.007)	0.53 (0.021)	17 (0.67) Int:68.58	DS	38.1 (1.5)	288	20	105	-	All	-
ML3-0	0.18 (0.007)	0.53 (0.021)	17 (0.67) Int:68.58	DS	38.1 (1.5)	288	20	105	V-0	All	-

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Type	Cond Width		Cond Thk mic(mil)	SS/ DS	Max Area Diam mm(in)	Solder Limits		Max Oper Temp C	Flame Class	Meets UL796 DSR	C T I
	Min mm(in)	Min Edge mm(in)				C	sec				
Single layer printed wiring boards.											
1	0.3 (0.012)	0.91 (0.036)	17 (0.67)	DS	38.1 (1.5)	288	20	130	-	▲	-
1-0	0.3 (0.012)	0.91 (0.036)	17 (0.67)	DS	38.1 (1.5)	288	20	130	V-0	▲	-
2	0.3 (0.012)	0.91 (0.036)	17 (0.67)	DS	38.1 (1.5)	260	20	105	-	▲	-
2-0	0.3 (0.012)	0.91 (0.036)	17 (0.67)	DS	38.1 (1.5)	260	20	105	V-0	▲	-
4	0.3 (0.012)	0.91 (0.036)	17 (0.67)	DS	38.1 (1.5)	288	15	130	-	▲	-
4-0	0.3 (0.012)	0.91 (0.036)	17 (0.67)	DS	38.1 (1.5)	288	15	130	V-0	▲	-

Marking: Company name or trademark  and type designation. May be followed by a suffix to denote factory identification.

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